

L Number	Hits	Search Text	DB	Time stamp
-	1221	257/779	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 09:57
-	1355	257/780	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/30 12:29
-	132	(metal adj bump, metal adj ball, solder adj ball) with (clean\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/30 14:23
-	724	257/781	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/30 16:19
-	529	257/772	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/30 17:29
-	41	(solder) with (out with (seal\$4 adj resin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/30 17:41
-	563	257/741	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/31 11:19
-	465	((high adj melt\$3) with (low adj melt\$3, eutectic)) with (solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 09:59
-	2	5591941.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 10:13